

## ETCHING MODULE $\mu$ CHEM-ECES



The etching unit  $\mu$ Chem-ECES is a sufficient wet chemical process tool for electrochemical etch-stop processes. The electrochemical etch-stop is one of the most cost-effective, convenient and precise technique for fabricating thin, mono-crystalline silicon membranes. It is based on the different etching potentials of n- and p-type doped silicon layers in alkaline etching solutions, such as potassium hydroxide (KOH). Because of the flexible arrangement and build-up, the etching system  $\mu$ Chem is the ideal tool either for industrial or R&D demands. Of course, customized solutions are available after clearing the technical details.

# ETCHING MODULE $\mu$ CHEM-ECES

## Data sheet

**Wafer Sizes:** up to 300mm

**Applications:** Membranes, MEMS, CMOS, Sensor,  
R&D or Production

### ETCHING MODULES

- Single Wafer Version
- Overflow circulation with filtration
- Potentiostat that keeps the p/n-junction in reverse bias and monitors the current over time
- Customized Chamber amount and Material Selection
- PLC controlled
- Touch Panel for easy operation

### RINSING MODULE

- Standard: Overflow Rinse
- Optional: QDR, SRD

### General OPTIONS

- Automatic Handling (Ready for Robot Handling)
- Internal Chemical Management
- Carrier Movement
- Integration of pre/post process cells as well
- Laminar-Flow-Units optional available
- Execution as fume hood
- FM 4910 proofed material

### BUILD-UP

- Material: PP white
- Door material: PVC transparent
- PFA tube with Flaretek Fittings
- Access Panel: Touch Panel

### OPERATING ELEMENTS

- All process operating elements are integrated into the front panel
- All electrical and pneumatically components are integrated in an independent compartment in the back side service area,
- DIW- and N<sub>2</sub>-Spray gun integrated in the working surface

